



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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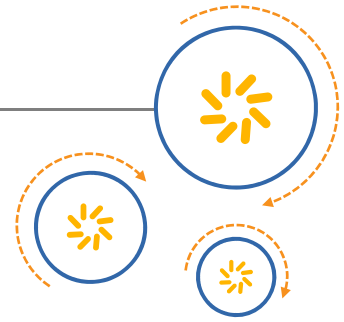
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Document Title: **Environmental Compliance Report - CSR6031AXX-ICXJ-R**  
 Product Code: **CSR6031AXX-ICXJ-R**  
 Cognidox Ref.: **CS-210562-RP**  
 Issue: **Issue 1**  
 Date Issued: **16-Nov-10**

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<b>CSR Product</b>	CSR6031AXX-ICXJ-R				<b>Product Environmental Status</b>	<b>Definition of EU RoHS:</b>	Product meets the requirements of Directive 2002/95/EC of the European Parliament and of the Council on the Restriction of Hazardous Substances.
<b>Package</b>	3.66 x 4.13 x 0.57mm WLCSP	<b>Material Environmental Status</b>	<b>Link to Lab Analysis Reports</b>		<b>CSR 'GREEN' Compliant</b>	<b>Definition of CSR 'GREEN':</b>	
<b>Die Size</b>	3620 x 4090 x 330µm	CSR 'GREEN'	<a href="#">CS-200300-RP</a>				
<b>Polymer Material</b>	PBO-HD8820	CSR 'GREEN'	<a href="#">CS-110053-RP</a>				
<b>RDL</b>	Ti/Cu/Cu	CSR 'GREEN'	<a href="#">CS-110063-RP</a>	<a href="#">CS-110061-RP</a>		<a href="#">CS-126498-RP</a>	
<b>UBM</b>	Ti/Cu/Cu	CSR 'GREEN'	<a href="#">CS-110063-RP</a>	<a href="#">CS-110061-RP</a>		<a href="#">CS-126498-RP</a>	
<b>Solder Balls</b>	0.3mm diam Sn/Ag/Cu 95.5/4.0/0.5	CSR 'GREEN'	<a href="#">CS-110027-RP</a>		<b>Env. Compliance Statement</b>		
					<a href="#">CB-001036-ST</a>		

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**MATERIAL DATA FORM**

Manufacturer name.	Total Mass of the Unit specified in (mg):	Unit / Comp. Description. (e.g. CHIPRES 0W125 1R0 J 1206)	Breakdown of component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name. (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass. (mg)	% weight with respect to homogenous material / sub mass	% weight with respect to whole package	Additional Information (e.g. complete polymeric Material Trade Name or metallic Material Standard). Please declare "No FR" when the polymeric material DOES NOT contain any flame retardants.	
CSR / ASE	17.98813	CSR6031AXX-ICXJ-R									
The data set forth herein have been derived using information supplied to CSR by its suppliers and is believed to be accurate on the date of preparation. However, CSR MAKES NO WARRANTY, EITHER EXPRESS OR IMPLIED, WITH RESPECT TO THE DATA AND DISCLAIMS ALL RELIABILITY FROM RELIANCE ON IT OTHER THAN THAT EXPRESSLY PROVIDED IN CSR ENVIRONMENTAL COMPLIANCE STATEMENTS - CB-001021-ST (RoHS Compliant Products) or CB-001036-ST (Green Products).	<b>Resist (2 layers)</b>			<b>HD8820 PBO</b>		sub mass	0.30426	100.00000%	1.69144%		
	PBO polymer resin			HD8820 PBO	PBO resin	Proprietary	0.30426	100.00000%	1.69144%		
	<b>Runner Metal Sputter (RDL)</b>						sub mass	0.27219	100.00000%	1.51316%	
				Sputtered Titanium	Titanium	7440-32-6	0.00323	1.18819%	0.01798%		
				Sputtered Copper	Copper	7440-50-8	0.01281	4.70532%	0.07120%		
				Plated Copper	Copper	7440-50-8	0.25615	94.10649%	1.42398%		
	<b>UBM Metal Sputter</b>						sub mass	0.13229	100.00000%	0.73542%	
				Sputtered Titanium	Titanium	7440-32-6	0.00075	0.57063%	0.00420%		
				Sputtered Copper	Copper	7440-50-8	0.00299	2.25976%	0.01662%		
				Plated Copper	Copper	7440-50-8	0.12854	97.16961%	0.71461%		
	<b>Solder Sphere-Pb-free ( sub mass )</b>				<b>0.3mm diam Sn/Ag/Cu</b>		sub mass	5.89522	100.00000%	32.77280%	
	Sn-Ag-Cu alloy			Tin (Sn)	Tin (Sn)	7440-31-5	5.62993	95.50000%	31.29803%		
	Sn-Ag-Cu alloy			Silver (Ag)	Silver (Ag)	7440-22-4	0.23581	4.00000%	1.31091%		
	Sn-Ag-Cu alloy			Copper (Cu)	Copper (Cu)	7440-50-8	0.02948	0.50000%	0.16386%		
	<b>Silicon Chip ( sub mass )</b>				<b>CMOS</b>		sub mass	11.38418	100.00000%	63.28717%	
CSR6026			Si	Silicon ( Si )	7440-21-3	11.38418	100.00000%	63.28717%			

**Total mass (g)**    17.98813    **100.00%**

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